

# For customer acceptance

Customer	date
Approved	
Comments	

The standard product specification may change without	Revision	1.2
The standard product specification may change without prior notice in order to improve performance or quality.	Engineering	
Please contact Display Future Ltd for updated specification and product status before design for the standard product or	Date	2018/01/4
elease of the order.	Our Reference	

## **REVISION RECORD**

REV NO.	REV DATE	CONTENTS	REMARKS
1.0	2018-01-04	Initial Release	

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## 3. APPLICATION

DVD player, UMPC, POS, MID

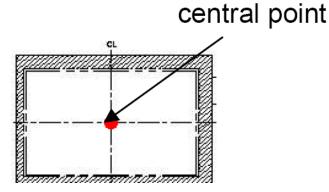
### 4. GENERAL SPECIFICATIONS

Composition: 5.7inch Capacitive Touch Panel (CTP). Interface:  $I^2C$  for the CTP.

ltem	Specification	Unit
Туре	Transparent type projected capacitive touch panel	
Input mode	Human's finger	
Finger	10	
Sensor Active Area	118.76(W)(typ.) x89.95(H)(typ.)	mm
Transparency	≧85%	%
Haze	≦2.0%	%
Origin Point	The upper left corner	
Hardness	7H (typ.) [by JIS K5400]	Pencil hardness
Report rate	Max: 122	Points/sec
Response time	15	ms
Point hitting life time	1,000,000 times min.	Note 1

Note 1: Use 8 mm diameter silicon rubber/force 3N to knock on the same point twice per

second (no-operating), after test function check pass.



## **5. ABSOLUTE MAXIMUM RATINGS**

Symbol	Description	Min	Тур.	Max	Unit	Notes
VCC1	Supply voltage	2.66	-	3.47	V	
VIO	DC input voltage	0	-	VCC1+0.3	V	

Symbol	Description	Min	Тур	Max	Unit	Notes
VCC1	Supply voltage	2.8	-	3.3	V	
GND	Supply voltage	-	0	-	V	
I	Active mode	-	13	15	mA	
Vih	Input H voltage	1.35	1.8	2.1	V	
VIL	Input L voltage	-0.3	0	0.45	V	

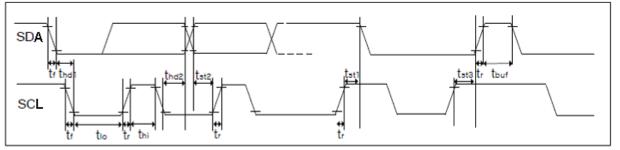
### 6. ELECTRICAL CHARACTERISTICS

### 7. TIMING SPECIFICATIONS 7.1 CTP Interface and Data Format [Slave address is 0x5D( 7 bit addressing )]

Communication protocol: I<sup>2</sup>C

Clock frequency : 100Khz (400Khz Fast mode)

Below is timing of I2C hardware circuit:

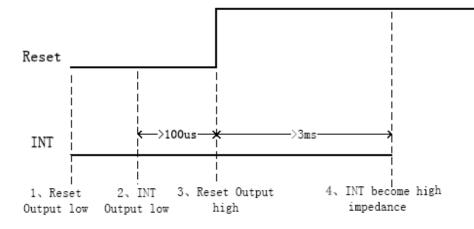


Test condition 1: 3.3V communication interface, 400Kbps, pull up resistor is 2K ohm

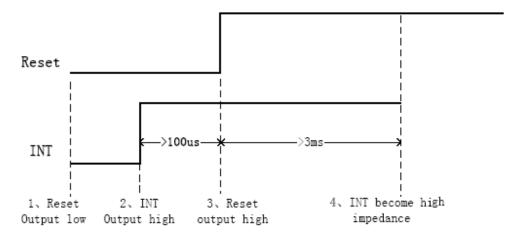
Parameter	Symbol	Min	Max	Unit
SCL low period	t <sub>lo</sub>	0.9	0.9	us
SCL high period	t <sub>hi</sub>	0.8	0.8	us
SCL setup time for START condition	t <sub>st1</sub>	0.4	0.4	us
SCL setup time for STOP condition	t <sub>st3</sub>	0.4	0.4	us
SCL hold time for START condition	t <sub>st1</sub>	0.3	0.3	us
SDA setup time	t <sub>st2</sub>	0.4	0.4	us
SDA hold time	t <sub>st2</sub>	0.4	0.4	us

GT927 has 2 sets of slave address 0xBA/0xBB or 0x28/0x29. Master can control Reset & INT pin to configure the slave address the slave address in power on initial state like following

### 7.1.1 Timing of setting slave address to 0xBA/0XBB:



#### 7.1.2 Timing of setting slave address to 0x28/0X29:



#### a) Data Transmission (ex: slave address is 0xBA/0xBB)

Communication is always initiated by master, A high-to-low transition of SDA with SCL high is a start condition.

All addresses words are serially transmitted to and from on bus in 8-bit words. GT927 sends a "0" to acknowledge when the address word is 0xBA/BB. This happens during the ninth clock cycle. If the slave address is not matched, GT927 will stay in idle state.

The data words are serially transmitted to and from in 9-bit words: 8-bit data + 1-bit ACK or NACK sent by GT927. Data changes during SCL high periods.

A low-to-high transition of SDA with SCL high is a stop condition. **b) Write Operations to GT927** (ex: slave address is 0xBA/0xBB)

s	Address_W	A C	Register_H	A C	Register_L	A C	Data_1	A C	 Data_n	A C	Е
		к		к		к	_	к	_	К	

### Write Operations

Please check above figure, master start the communication first, and then sends address words 0XBA for a write operation.

After receiving ACK from GT927, master sends out register address word in 16-bit, and then the data word in 8-bit, which is going to be wrote into GT927.

GT927's address pointer will be automatically added 1 after write operation, so master can sequential write in one operation. When operation finished, master stop the communication.

#### c) Read Operations to GT927 (ex: slave address is 0xBA/0xBB)

s	Address_W	A C K	Register_H	A C K	Register_L	A C K	Е	S	Address_R	A C K	Data_1	A C K		Data_n	N E C K
		►Se	t start register	addre	55 🗲						→ Re	ad dat	ia 🔶		

#### Read operation

Please check above figure, master start the communication first, and then sends address words 0xBA for a write operation.

After receiving ACK from GT927, master sends out register address word in 16-bit, to set GT927's address pointer. After receiving ACK, master sends out a start signal once again, start the read operation with command: 0xBB, and read data word from GT927 in 8-bit.

GT927 also supports sequential read operation, and the default setting is sequential read mode. Master shall send out ACK when receiving successfully in every data word, master sends NACK after getting all the data required, then sends stop signal to finish the communication.

### 7.1.3 Register Information of GT927

	al line Older (white Oh	y)								
Addr	Name	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	
0x8040	Command	0: read status of coordinate 1:D-value 2: software reset 3: benchmark update 4: benchmark calibration 5: screen off								
0x8041	LED_Control		Contro	l word u	nder co	ntrol of	touch ke	y LED lig	ght	
0x8042	Proximity_En	Proximity switch								

## a) Real Time Order (Write Only)

b) Configuration Information (R/W)											
Addr	Name	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0		
0x8047	Config_Version		Vers	sion numl	per of c	onfigui	ation do	cument			
0x8048	X Output Max_L			N		le of X	ovic				
0x8049	X Output Max_H			IV	lax valu		axis				
0x804A	Y Output Max_L	Max value of Y axis									
0x804B	Y Output Max_H										
0x804C	Touch Number	Reserved Touch number: 1~5									
0x804D	Module_Switch1	Reser	ved S	tretch_ra	nk	X2Y	Sito		trigger ethod		
0x804E	Module_Switch2		R	eserved			Т	ouch_K	еу		
0x804F	Shake_Count		Res	erved				shake co			
0x8050	Filter	First	_Filter				tering va dow, coe				
0x8051	Large_Touch			Numbe	er of tou	uch in la	arge are	a			
0x8052	Noise_Reduction		Reserv	ed	Valu	le of no	oise elim is 1	•	coefficient		
0x8053	S_Touch_Level		Tł	nreshold o	of touch	n grow	out of no	othing			
0x8054	S_Leave_Level			nreshold o							
0x8055	Low_Power_Control	Reserved Time to low power consumption(0~15s)							5s)		
0x8056	Refresh_Rate	Reserved Coordinate report rate(Cycle 5+N ms)							e(Cycle:		
0x8057	x_threshold				Pos	served					
0x8058	y_threshold				Nea	serveu					
0x8059	X_Speed_Limit			Para	ameter	ofsnee	ed limit				
0x805A	Y_Speed_Limit										
0x805B	Space	-		boarder-		Blank area of boarder-bottom					
0x805C	•	Blank	carea of	boarder-			nk area o	of board	er-right		
0x805D	NC					served					
0x805E	NC					served					
0x805F	NC					served					
0x8060	NC					served					
0x8061	NC					served		•			
0x8062	Drv_GroupA_Num	All_Dr		Reserv			ver_Gro				
0x8063	Drv_GroupB_Num		served	D_F			ver_Gro				
0x8064	Sensor_Num	Senso	or_Grou	p_B_Num			sor_Gro				
0x8065	FreqA_factor		Group	A_Freque	nce =N	/ultiplie	r factor	*baseba			
0x8066	FreqB_factor	Driver frequency double frequency coefficient of Driver group B GroupB_Frequence =Multiplier factor *baseband									
0x8067	Pannel_BitFreqL	Basa		Driver gro							
0x8068	Pannel_BitFreqH	Dase		Dirver gro		5(1520			4000HZ)		
0x8069	Pannel_Sensor_TimeL	Tim	a inton	al of the r	aihaur	ing two	driving	signal/L	nit: us)		
0x806A	Pannel_Sensor_TimeH								int. us <i>j</i>		

			Deve				
0x806B	Pannel_Tx_Gain	Reserved	Panne	I_Drv_outp 4 gears	<b>-</b>		nel_DAC_Gain
0x806C	Pannel_Rx_Gain	Pannel_PGA _C	Panne	I_PGA_R	Panne _Vo	el_Rx cmi	Pannel_PGA _Gain
0x806D	Pannel_Dump_Shift	Reserved			Magnification coefficient of origi value(The Nth power of 2)		
0x806E	Drv_Frame_Control	Reserved	S	SubFrame_ Num	Drv	Re	peat_Num
0x806F	NC			Reserv	Reserved		
0x8070	NC			Reserv	eserved		
0x8071	NC			Reserv			
0x8072	Stylus_Tx_Gain	Und	defined(ii	nvalid whe	n stylus	_priority	y=0)
0x8073	Stylus_Rx_Gain	Und	defined(ii	nvalid whe	n stylus	_priority	y=0)
0x8074	Stylus_Dump_Shift	Und	defined(ii	nvalid whe	n stylus	_priority	y=0)
0x8075	Stylus_Touch_Level	Und	defined(ii	nvalid whe	n stylus	_priority	y=0)
0x8076	Stylus_Leave_Level	Und	defined(ii	nvalid whe	n stylus	_priorit	y=0)
0x8077	Stylus_Control	Pen ı	node es	cape time	out perio	od(Unit	: Sec)
0x8078	NC			Reserv	ved		
0x8079	NC			Reserv	ved		
0x807A	Freq_Hopping_Start	Frequency	hopping	start frequ 100KH		nit: 2KH	lz,50means
0x807B	Freq_Hopping_End	Frequency hopping stop frequency(Unit: 2KHz,150means 300KHz)			z,150means		
0x807C	Noise_Detect_Tims	Detect_Stay_Times Detect_Confirm_Times			_Times		
0x807D	Hopping_Flag	Hop_En		Reserved		Detect	Time_Out
0x807E	Hopping_Threshold	Large_Nois					Threshold
0x807F	Noise Threshold	Threshold of noise level			-		
0x8080	NC			Reserv			
0x8081	NC			Reserv	ved		
0x8082	Hopping_seg1_BitFreqL	Frequency	hopping	segment b	and 1 c	entral fi	requency(for
0x8083	Hopping_seg1_BitFreqH			driver A			
0x8084	Hopping_seg1_Factor	Frequency h	opping s	egment 1	central f	requen	cy coefficient
0x8085	Hopping_seg2_BitFreqL	Frequency	hopping	segment b	and 2 c	entral fi	requency(for
0x8086	Hopping_seg2_BitFreqH	driver A/B)					
0x8087	Hopping_seg2_Factor	Frequency hopping segment 2 central frequency coeffici		cy coefficient			
0x8088	Hopping_seg3_BitFreqL	Frequency	hopping	segment b	and 3 c	entral fi	requency(for
0x8089	Hopping_seg3_BitFreqH			driver A	€∕B)		
0x808A	Hopping_seg3_Factor						cy coefficient
0x808B	Hopping_seg4_BitFreqL	Frequency	hopping	segment b	and 4 c	entral fi	requency(for
0x808C	Hopping_seg4_BitFreqH			driver A	/		
0x808D	Hopping_seg4_Factor						cy coefficient
0x808E	Hopping_seg5_BitFreqL	Frequency	hopping			entral fi	requency(for
0x808F	Hopping_seg5_BitFreqH			driver A			
0x8090	Hopping_seg5_Factor	Frequency h	opping s	egment 5	central f	requen	cy coefficient
0x8091	NC			Reserv			
0x8092	NC			Reserv			
0x8093	Key1	Key 1 Position: 0~255 valid(0 means no touch, it means independent touch key when 4 of the keys are 8 multiples)					
0x8094	Key2	Key 2 position			. /		
0x8095	Key3	Key 3 position					
0x8096	Key4	Key 4 position					
0x8097	Key_Area	Time limit for long press(1~16s) Touch valid interval setti 0~15 valid					
0x8098	Key_Touch_Level	•		threshold of	of touch		
	· · · -						

0x8099	Key_Leave_Level		Key threshold o	f touch ke	ev
		KeySens_1(sensitivity coefficient of key			
0x809A	Key_Sens	1,same below)			KeySens_2
0x809B	Key_Sens			KeySens_4	
0x809C	Key_Restrain	Reserved Reserved			Reserved
0x809D	NC		Reserv	red	
0x809E	NC		Reserv	red	
0x809F	NC		Reserv		
0x80A0	NC		Reserv		
0x80A1	NC		Reserv	1	
0x80A2	Proximity_Drv_Select	driving c			v_End_Ch(End channel)
0x80A3	Proximity_Sens_Select		(start channel of direction)	Ser	ns_End_Ch(End channel)
0x80A4	Proximity_Touch_Level		oximity effective t		
0x80A5	Proximity_Leave_Level		ximity ineffective		
0x80A6	Proximity_Freq_Factor	Frequency	mollification of pr	oximity se	ensing channel
0x80A7	Proximity_BitFreqL	Rase fr	equency of provin	nitv sansii	na channel
0x80A8	Proximity_BitFreqH	Base frequency of proximity sensing channel			
0x80A9	Proximity_Sensor_TimeL				
0x80AA	Proximity_Sensor_Time H	Time interval between proximity adjacent driving signal			nt driving signal
0x80AB	Proximity_Tx_Gain		Driving gain of		
0x80AC	Proximity_Rx_Gain		Driving gain of		
0x80AD	Proximity_Dump_Shift	Reserved			of proximity original ower of 2)
0x80AE	NC	Reserved			
0x80AF	NC		Reserv	red	
0x80B0	NC		Reserv	red	
0x80B1	NC		Reserv	red	
0x80B2	NC		Reserv	red	
0x80B3	NC		Reserv		
0x80B4	NC		Reserv	red	
0x80B5	NC		Reserv		
0x80B6	NC		Reserv	red	
0x80B7~	Sensor_CH0~	Correc	sponding channel	no of IT	O Sensor
0x80C4	Sensor_CH13				
0x80C5~	NC	Reserved			
0x80D4		i teseiveu			
0x80D5~	Driver_CH1~	Corresponding channel no. of ITO Driver0			O Driver0
0x80EA	Driver_CH21				
0x80EB~	NC		Reserv	red	
0x80FE					ation
0x80FF	Config_Chksum	Check of configuration information			
0x8100	Config_Fresh	Updated configuration(by master control)			

		tormation						
Addr	bit7	bit6	bit5	bit4	bit3	bit2	bit1	bit0
0x8140		Product ID(Lowest Byte, ASCII code 6)						
0x8141		Product ID(Third Byte, ASCII code 0)						
0x8142		Product ID(Second Byte, ASCII code 0)						
0x8143		Product ID(Highest Byte, ASCII code 9)						
0x8144					oyte1)(Low			
0x8145			Firmwar	e version(b	yte2)(High	Byte)		
0x8146		x coordir	nate resolut	ion(low byt	e)(current c	output reso	lution)	
0x8147			x coord	linate resol	ution(high b	oyte)		
0x8148			y coord	dinate reso	lution(low b	yte)		
0x8149			y coord	linate resol	ution(high b	oyte)		
0x814A		Ve	endor_id(cu	rrent modu	Ile choice in	formation)		
0x814B				Reser	ved			
0x814C			ge	sture type	Reserved)			
0x814D					(Reserved)			
0x814E	buffer status	Large detect	Proximity		HaveKey	num	ber of tou	ch points
0x814F				track	id			
0x8150			point		nate(low by	ie)		
0x8151					ate(high by			
0x8152					nate(low by			
0x8153					ate(high by			
0x8154				oint 1 size				
0x8155				oint 1 size(				
0x8156			F	Reser				
0x8157				track				
0x8158		point 2 x coordinate(low byte)						
0x8159	point 2 x coordinate(low byte)							
0x815A	point 2 y coordinate(low byte)							
0x815B	point 2 y coordinate(high byte)							
0x815C	point 2 size(low byte)							
0x815D				oint 2 size(				
0x815E			P	Reser				
0x815F				track				
0x8160		point 3 x coordinate(low byte)						
0x8161		point 3 x coordinate(low byte)						
0x8162					nate(low by			
0x8163								
0x8164		point 3 y coordinate(high byte) point 3 size(low byte)						
0x8165	point 3 size(high byte)							
0x8166		Reserved						
0x8167		track id						
0x8168	point 4 x coordinate(low byte)							
0x8169	point 4 x coordinate(high byte)							
0x816A	point 4 y coordinate(low byte)							
0x816B	point 4 y coordinate(high byte)							
0x816C	point 4 size(low byte)							
0x816D	point 4 size(low byte)							
0x816E	Reserved							
0x816F	track id							
0x8170		point 5 x coordinate(low byte)						
0x8170		point 5 x coordinate(low byte)						
0x8171								
070172	point 5 y coordinate(low byte)							

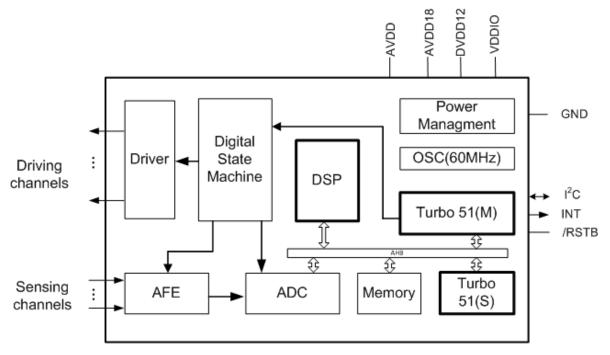
## c) Coordinates Information

0x8173	point 5 y coordinate(high byte)			
0x8174	point 5 size(low byte)			
0x8175	point 5 size(high byte)			
0x8176	Reserved			
0x8177	track id			
0x8178	point 6 x coordinate(low byte)			
0x8179	point 6 x coordinate(high byte)			
0x817A	point 6 y coordinate(low byte)			
0x817B	point 6 y coordinate(high byte)			
0x817C	point 6 size(low byte)			
0x817D	point 6 size(high byte)			
0x817E	Reserved			
0x817F	track id			
0x8180	point 7 x coordinate(low byte)			
0x8181	point 7 x coordinate(high byte)			
0x8182	point 7 y coordinate(low byte)			
0x8183	point 7 y coordinate(high byte)			
0x8184	point 7 size(low byte)			
0x8185	point 7 size(high byte)			
0x8186	Reserved			
0x8187	track id			
0x8188	point 8 x coordinate(low byte)			
0x8189	point 8 x coordinate(high byte)			
0x818A	point 8 y coordinate(low byte)			
0x818B	point 8 y coordinate(high byte)			
0x818C	point 8 size(low byte)			
0x818D	point 8 size(high byte)			
0x818E	Reserved			
0x818F	track id			
0x8190	point 9 x coordinate(low byte)			
0x8191	point 9 x coordinate(high byte)			
0x8192	point 9 y coordinate(low byte)			
0x8193	point 9 y coordinate(high byte)			
0x8194	point 9 size(low byte)			
0x8195	point 9 size(high byte)			
0x8196	Reserved			
0x8197	track id			
0x8198	point 10 x coordinate(low byte)			
0x8199	point 10 x coordinate(high byte)			
0x819A	point 10 y coordinate(low byte)			
0x819B	point 10 y coordinate(high byte)			
0x819C	point 10 size(low byte)			
0x819D	point 10 size(high byte)			
0x819E	Reserved			
0x819F	Keyvaule			

### 8. Pin Connections

No.	Name	I/O	Description	
1	NC	-	No connection	
2	SCL	I	I <sup>2</sup> C Clock	
3	SDA	I/O	I <sup>2</sup> C Data	
4	NC	-	No connection	
5	INT	0	nterrupt output	
6	GND	Р	Bround	
7	VCC1	Р	Power supply Voltage	
8	/RESET	I	Reset active low	
9	NC	-	No connection	

### 9. BLOCK DIAGRAM



### **10. Appearance Specification**

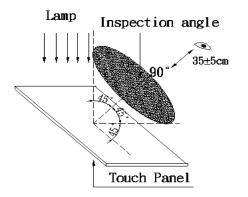
### **10.1 Process/Content:**

- 10.1.1Inspection equipment : fluorescent lamp <sup>,</sup> functional test jig <sup>,</sup> magnifying glass, Vernier caliper, ESD wrist strap.
- 10.1.2 Environment demand
  - 1.2.1 Temperature  $: 25\pm5^{\circ}C$
  - 1.2.2 Humidity : 30-75%RH
  - 1.2.3 Luminance : Fluorescent light (appearance : 800-1200UXL function : 100-500UXL)
- 10.1.3 Inspection process
  - 1.3.1 Inspect distribution operation
  - 1.3.2 Shift team leader is in charge of distributing work when work order goes to OQC inspection of finished products
  - 1.3.3 Products of great emergency or especially asked by customer should be finished in advance.
  - 1.3.4 All the items should be fully inspected before shipment.
  - 1.3.5 The inspection standard & specification should be carried out according to customer's demand. If customer has no other standard & specification, just stick to this one.
- 10.1.4 Sampling plan
  - 1.4.1 Do tests regularly according to MIL-STD-105E. Single sampling plan is arrived out according to Level.
  - 1.4.2 Defect definition
    - 1.4.2.1 Major defect is inspected according to AQL 0.40%.
    - 1.4.2.2 Minor defect is inspected according to AQL 0.40%.

### 10.1.5 Appearance inspection

1.5.1 Appearance inspection method

Inspection angle spacing : 30-40cm



Item	Spec		Statement
	Spec	Q'ty allowed	
Foreign material	D>0.5mm	0	
Punctiform	0.3mm≦D≦0.5mm	5	D= (L + W) / 2
	D<0.3mm	Di sregarded	
	Spec	Q'ty allowed	
Faultan material	W>0.1mm L>5mm	0	
Foreign material Linear	0.05mm≦W≦ 0.1mm L≦5mm	5	L : Long W : Width
	₩<0.05mm	Di sregarded	
Image uniformity	Gray color can be seen on RGB through ND5%		

## 1.5.2 Appearance inspection standard

	Spec	Q'ty allowed	$\sim$
TP scratch	W>0.07mm L>7mm	0	
	W≦0.07mm L≦7mm	5	L
	Spec	Q'ty allowed	
TP dented spot	D>0.5mm	0	L D= (L + W) / 2
	0.3mm≦D≦0.5mm	5	
TP overflows or lacks of glue	<b>±0</b> .45mm		

Surface broken	X<2mm Y<2mm Z <glass< th=""><th>a the second sec</th></glass<>	a the second sec
Edge broken	X<2mm Y<2mm Z <glass< td=""><td></td></glass<>	
Rift	Not allowed	
Bubble appears in protection film	D>10mm N=0 5≦D≦10mm N=2 D<5 disregarded	
TP deviation	According to the specifications of customer's drawing	
Bubbl e	D≤0.2mm disregarded 0.2mm < D≤0.3mm N≤2 0.2mm < D pot allowed	
	O.3mm <d allowed<br="" not="">No influence on appearance and function in invisible area OK</d>	
Printing ink	<pre>No light leak Silk-screen saw tooth : S≦0.1 disregarded 0.1mm≦S≦0.15mm N=5 S&gt;0.15 ng LOGO break line NG Script dim, printed backwards , no printing in wrong place</pre>	
Finger print	Not allowed	
Stain	Stain on surface can be removed OK Bonding surface has no influence on appearance and function OK Can't be removed & not allowed	
Protection film	Bent isn't allowed No lift up Bent is allowed L<10MM N≦5	

### **11. QUALITY ASSURANCE**

### **11.1 Test Condition**

- 11.1.1 Temperature and Humidity (Ambient Temperature) Temperature:  $25 \pm 5^{\circ}$ C Humidity:  $65 \pm 5\%$
- 11.1.2 Operation

Unless specified otherwise, test will be conducted under function state.

11.1.3 Container

Unless specified otherwise, vibration test will be conducted to the product itself without putting it in a container.

11.1.4 Test Frequency

In case of related to deterioration such as shock test. It will be conducted only once.

	Reliability Test Item & Level	Test Level
No.	Test Item	
1.	High Temperature Storage Test	T = $80$ °, C 120 hrs after 1 hrs at room temperature and test.
2.	Low Temperature Storage Test	T = -30, $^{\circ}$ 120hrs after 1 hrs at room temperature and test.
3.	High Temperature and High Humidity Storage Test	T= $40^{\circ}$ C , 90%RH,120hrs after 24 hrs at room temperature and test.
4.	Thermal Cycling Test (No operation)	-30 $^\circ\!\!C$ 30min ~ 80 $^\circ\!\!C$ 30 min , 100 Cycles after 24 hrs at room temperature and test.
5.	Vibration Test (No operation)	Frequency :10 ~ 55 HZ Amplitude :1.5 mm Sweep time : 11 mins Test Period: 6 Cycles for each direction of X, Y, Z
6.	ESD TEST	Air Discharge:±15KV Indirect Contact Discharge:±8KV

### 11.1.5 Test Method

#### **12. PRECAUTIONS IN USE CTP**

#### 1. ASSEMBLY PRECAUTIONS

- Since Touch Panel is consist of glass, please be careful your hands to be injured during handing. You must wear gloves during handing.
- (2) Do not touch, push or rub the exposed touch panel, tweezers or anything harder than HB pencil lead. And please do not rub with dust clothes with chemical treatment.
- (3) Do not stack the touch panels together. Do not put heavy objects on touch panel.
- (4) Please do not take a CTP to pieces and reconstruct it. Resolving and reconstructing modules may cause them not to work well.
- (5) Please excessive force or strain to the panel or tail is prohibited, Do not lift touch panel by cable(FPC).
- (6) Use clean sacks or glove to prevent fingerprints and/or stains left on the panel. Extra attention and carefulness should be taken while handling the glass edge.
- (7) Please pay attention for the matters stated below at mounting design of touch panel enclosure. Enclosure support to fix touch panel must be out of active area.(do not design enclosure presses the active area to protect from miss put)
- 2. OPERATING PRECAUTIONS
  - (1) Please be sure to turn off the power supply before connecting and disconnecting signal input cable.
  - (2) Please do not change variable resistance settings in CTP. They are adjusted to the most suitable value. If they are changed, it might happen CTP does not satisfy the characteristics specification
  - (3) Be careful for condensation at sudden temperature change. Condensation makes damage to sensor or electrical contacted parts.
  - (4) CTP has high frequency circuits. Sufficient suppression to the electromagnetic interference shall be done by system manufacturers. Grounding and shielding methods may be important to minimize the interference.
  - (5) Touch the panel with your finger or stylus only to assure normal operation. Any sharp edged or hard objects are prohibited.
  - (6) Operate the panel in a steady environment. Abrupt variation on temperature and humidity may cause malfunction of the panel.
- 3. ELECTROSTATIC DISCHARGE CONTROL
  - (1) The operator should be grounded whenever he/she comes into contact with the CTP. Never touch any of the conductive parts such the copper leads on the FPC and the interface terminals with any parts of the human body.

- (2) The CTP should be kept in antistatic bags or other containers resistant to static for storage.
- (3) Only properly grounded soldering irons should be used.
- (4) If an electric screwdriver is used, it should be well grounded and shielded from commentator sparks.
- (5) The normal static prevention measures should be observed for work clothes and working benches; for the latter conductive (rubber) mat is recommended
- (6) Since dry air is inductive to statics, a relative humidity of 50-60% is recommended.
- STORAGE PRECAUTIONS
- (1) When you store touch panel for a long time, it is recommended to keep the temperature between  $0^{\circ}C-40^{\circ}C$  without the exposure of sunlight and to keep the humidity less than 90%RH.
- (2) Please do not leave touch panel in the environment of high humidity and high temperature such as 60°C 90%RH
- (3) Please do not leave touch panel in the environment of low temperature; below -20°C.
- 6. OTHERS

5.

7.

- For the packaging box, please pay attention to the followings: a. Please do not pile them up more than 5 boxes. (They are not
- designed so.) And please do not turn over.
- b. Please handle packaging box with care not to give them sudden shock and vibrations. And also please do not throw them up.
- c. Packing box and inner case for CTP are made of cardboard. So please pay attention not to get them wet. (Such like keeping them in high humidity or wet place can occur getting them wet.)

#### LIMITED WARRANTY

Unless otherwise agreed between Display Future and customer, Display Future will replace or repair any of its CTP which is found to be defective electrically and visually when inspected in accordance with Display Future acceptance standards, for a period on one year from date of shipment. Confirmation of such date shall be based on freight documents. The warranty liability of Display Future is limited to repair and/or replacement on the terms set forth above. Display Future will not responsible for any subsequent or consequential events.

### **13. OUTLINE DRAWING**

